

L Number	Hits	Search Text	DB	Time stamp
1	177	( 438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 14:57
2	27	rcc and bump	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
4	52	rcc and solder	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
-	83	((flip-chip and resin) and photosensitive) and laminated	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 11:42
-	4	((flip-chip and resin) and photosensitive) and rcc	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:00
-	5	6255039.URPN.	USPAT	2003/03/16 09:36
-	11	("3319317"   "3778900"   "4642160"   "4672020"   "4915983"   "4952528"   "5334487"   "5354593"   "5451721"   "5595858"   "5744285").PN.	USPAT	2003/03/16 09:39
-	202	(flip-chip and resin) and photosensitive	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:14
-	690	438/108.ccls.	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 10:56
-	338	438/108.ccls. and resin	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:25
-	328	( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 10:56
-	163	(( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:25
-	0	20020070459.URPN.	USPAT	2003/03/16 10:36



	25	(rcc and solder) not ((( 438/637.ccls. and resin) not ((( 438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not ((( 438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) rcc and bump	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/16 11:17
	19		USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:32



-	208	(( 438/108.ccls. and resin) not ((flip-chip and resin and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/02 17:26
-	117	((flip-chip and resin) and photosensitive) and laminated	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 11:43

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2	27	rcc and bump	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
4	52	rcc and solder	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 16:35
5	41	(( 438/637.ccls. and resin) not ((( 438/613.ccls. and resin) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) not ((( 438/108.ccls. and resin) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)) not ((flip-chip and resin) and photosensitive)) and (cure or thermoset\$5 or uv or "exposure mask" or irradiat\$4)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/03/04 17:16